SEP 1 7, 2001 E

# UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner:

Atty Docket No.: 1047

BOX DAC

In re:

Applicant:

**BERNHARD LUCAS** 

Serial No.:

09/488,398

Filed:

January 20, 2000

I hereby cortify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents,

Washington, D.C. 20231.

n, D.C. 20231. 9/13/0/

# PETITION TO WITHDRAW HOLDING OF ABANDONMENT

August 16, 2001

Honorable Commissioner of Patents and Trademarks Washington, D.C. 20231

The subject application became abandoned for failure to reply to the Notice to File Missing Parts mailed on March 21, 2000.

Applicant herewith states that it did not receive a Notice to File Missing Parts mailed on March 21, 2000 or on any other day.

In fact, on November 7, 2000, applicant caused to be filed a status request indicating that applicant had not yet received a Notice to File Missing Parts.

The undersigned herewith states that he has carefully reviewed the file of the subject application and there is no indication therein that a Notice to File Missing Parts was ever received.

Applicant further submits herewith the appropriate pages from the Office

Docket book upon which the term for responding to the Notice to File Missing Parts would have been indicated had the Notice to File Missing Parts been received.

Applicant further submits herewith a declaration in response to the requirement to file a Notice of Missing Parts and requests that any fee be debited to the account of the undersigned, #19-4675.

Withdrawal of the Notice of Abandonment of the subject application is respectfully requested.

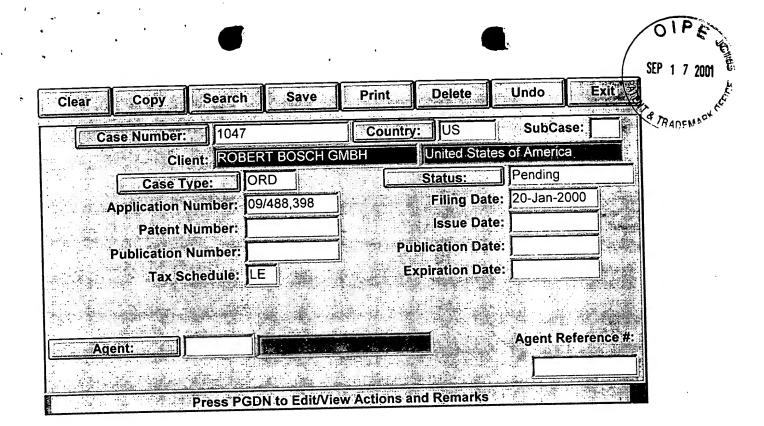
Respectfully submitted,

Michael J. Strik

Attorney for Applicant

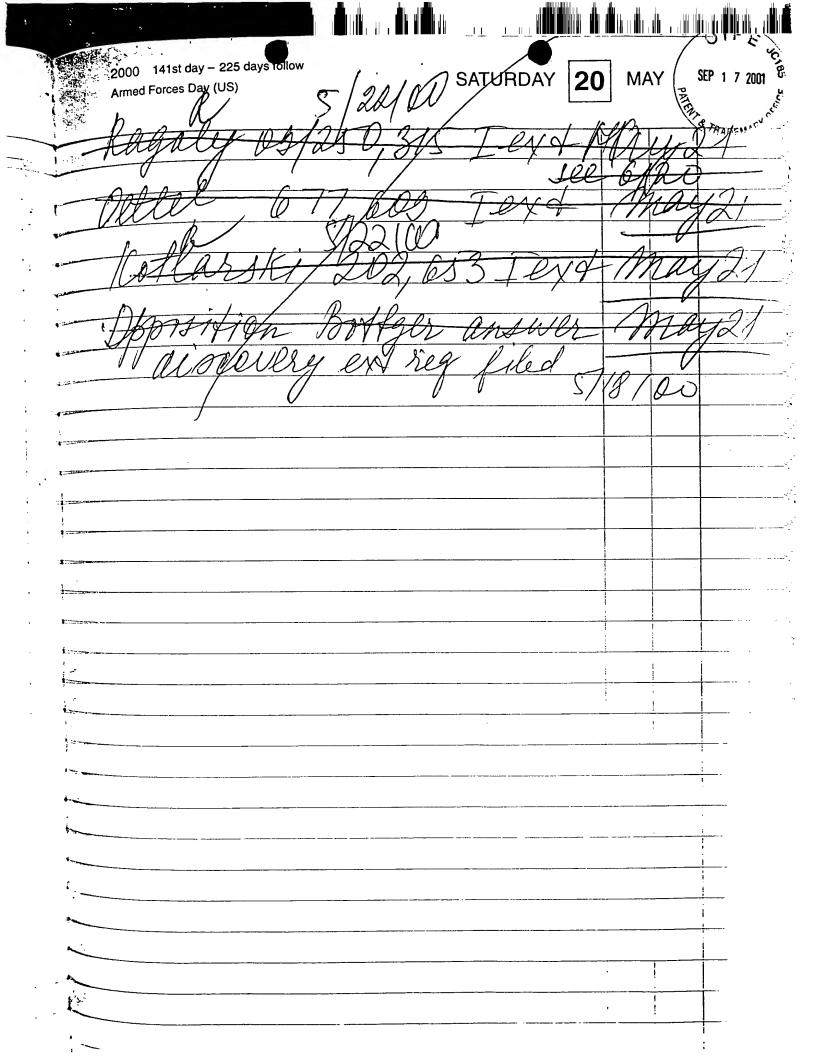
Reg. No.: 27233 103 East Neck Road

Huntington, New York 11743



SEP 1 7 2001

Case Number: 1047 Action Taken -Due------Date Indicator 8 Action(s) Due 17-Jan-2000 **Due Date** 21-Jan-2000 Mail by date 20-Jan-2000 21-Jan-2000 Due Date Priority 20-Apr-2000 Due Date Information Disclosure Stmnt **Due Date** 20-Jul-2000 Foreign Filing Reminder 08-Nov-2000 Due Date 08-Nov-2000 Filing IDS Final 20-Jan-2001 Foreign Filing Due Application Sta Follow Up Date 08-May-2001 Due Date 08-Nov-2000 Due Date 20-Jul-2001 Application Status Check Remarks: Last Update: 28-Mar-2000 Date Created: 03-Jan-2000 User ID: MICHAEL S





### United States Patent and Trademark Office

COMMISSIONER FOR PATENTS
UNITED STATES PATENT AND TRADEMARK OFFICE
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APPLICATION NUMBER FILING DATE FIRST NAMED APPLICANT ATTY. DOCKET NO./TITLE 09/488,398 01/20/2000 Bernhard Lucas 1047

09/488,398

Striker Striker & Stenby 103 East Neck Road Huntington, NY 11743



CONFIRMATION NO. 4407
ABANDONMENT/TERMINATION
LETTER

\*OC00000006362631\*

Date Mailed: 07/31/2001

# NOTICE OF ABANDONMENT UNDER 37 CFR 1.53 (f) OR (g)

The above-identified application is abandoned for failure to timely or properly reply to the Notice to File Missing Parts (Notice) mailed on 03/21/2000.

· No reply was received.

A petition to the Commissioner under 37 CFR 1.137 may be filed requesting that the application be revived.

Under 37 CFR 1.137(a), a petition requesting the application be revived on the grounds of UNAVOIDABLE DELAY must be filed promptly after the applicant becomes aware of the abandonment and such petition must be accompanied by: (1) an adequate showing of the cause of unavoidable delay; (2) the required reply to the above-identified Notice; (3) the petition fee set forth in 37 CFR 1.17(I); and (4) a terminal disclaimer if required by 37 CFR 1.137(c).

Under 37 CFR 1.137(b), a petition requesting the application be revived on the grounds of **UNINTENTIONAL DELAY** must be filed promptly after applicant becomes aware of the abandonment and such petition must be accompanied by: (1) a statement that the entire delay was unintentional; (2) the required reply to the above-identified Notice; (3) the petition fee set forth in 37 CFR 1.17(m); and (4) a terminal disclaimer if required by 37 CFR 1.137(c).

Any questions concerning petitions to revive should be directed to "Office of Petitions" at (703) 305-9282.

A copy of this notice MUST be returned with the reply.

Customer Service Center

Initial Patent Examination Division (703) 308-1202

PART 1 - ATTORNEY/APPLICANT COPY



BE IT KNOWN that WE, Bernhard LUCAS, Frank SCHATZ, Juergen SEIZ, Heinz EISENSCHMID, Andreas KUGLER and Achim DIETERICH, citizens of Germany, whose post office addresses and residencies are, respectively, Zehenderstrasse 2, 74354 Besigheim, Germany; Tellstrasse 29, 70806

Kornwestheim, Germany; Baumbluete 11, 73642 Welzheim, Germany; Ludwigshafener Strasse 7, 70499 Stuttgart, Germany; Teckstrasse 13, 73553 Alfdorf, Germany; and Spielhof 25, 71540 Murrhardt, Germany; have invented a certain new and useful

# 10 CIRCUIT DEVICE WITH A CONTACT ELEMENT FOR ELECTRICALLY CONNECTING A WAVE GUIDE AND A CONDUCTOR STRIP IN A NEARLY STRESS-FREE MANNER

of which the following is a complete specification thereof:

### **BACKGROUND OF THE INVENTION**

### 1. Field of the Invention

The present invention relates to a circuit device with a contact element for electrically connecting a wave guide to a conductor strip.

### 2. Prior Art

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A so-called stepping transformer, whose geometry is substantially determined by the wavelength of the frequencies used, is employed in high frequency circuitry in a frequency range over 50 GHz at the junction between a wave guide and conductor strip circuit elements.

Usually an electrical connection of the final stage of the stepping transformer to the conductor strip circuit device is required. This electrical connection is, for example, accomplished by glued conducting small gold bands. These small gold bands are either mounted over a corner or on the bottom side of the final stage. This fabrication method is very expensive. Furthermore the electrical connection is put under great mechanical stress by possible relative motion due to differing thermal expansion of the metallic wave guide and the dielectric conductor strip substrates.

### Summary of the Invention

It is an object of the present invention to provide a circuit device with a contact element for electrically connecting the wave guide to a conductor strip, which does not have the above-mentioned disadvantage.

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According to the invention the contact element electrically connects the wave guide with the conductor strip by means of two contacting areas and is made from an accurately prefabricated coil spring having predetermined reproducible properties. This coil spring is connected at one of the contacting areas to the conductor strip or to the wave guide by means of an electrically conductive glue and another of the contacting areas is a sliding contact whereby the coil spring is pre-tensioned; or is provided by an electrically conductive glue or adhesive portion, whereby the coil spring is bent into a U-shape; or is provided with a highly flexible electrically conductive adhesive section.

This type of electrical connection is easy to make. Different thermal expansion properties of the different materials are easily and satisfactorily compensated.

Advantageous additional embodiments are set forth in the dependent claims. Their features, in so far as it is appropriate and significant, may of course be combined with each other.

The sliding contact can move with the participating structural elements without experiencing significant mechanical stresses due to relative motions

(originating, for example, from differing thermal expansion properties). Without the device according to the invention the contacting areas would be subjected to impermissibly large mechanical stresses. The motion is compensated by the coil spring itself and/or by the pre-tensioned sliding contact in a nearly stress-free manner.

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Relative motion of the parts occurs without tearing off the contact element.

The contact junction is reproducible and not dependent on the bonding form and processes. Thus the electrical tuning between the wave guide and the conductor strip is reproducible.

The coil spring for applications in the highest frequency engineering is especially small (length, about 100 to 200  $\mu$ m, thickness about 50  $\mu$ m). The coil spring is formed with very great accuracy, particularly as a so-called MIGA coil spring(MIGA = microgalvanic). UV depth lithography or comparable methods of structuring polymers in combination with multilayer microgalvanic methods are suitable for making the coil spring. Laser processing or high precision punching or stamping can be suitable for making the coil spring.

Thus simple but precise or exact fabrication methods are possible for the coil spring. Tolerances of <  $\pm$  10  $\mu$ m may be obtained for the above-described contact element with UV depth lithography. A wide range of materials can be selected so that special spring properties can be obtained. An automatic mounting of the coil spring and easy manufacture of the electrical connection are possible. Several coil springs can be economically made at the same time in a batch process (which means for many applications).

### **Brief Description of the Drawing**

The objects, features and advantages of the invention will now be illustrated in more detail with the aid of the following description of the preferred embodiments, with reference to the accompanying figures in which:

Figure 1 is a schematic cutaway cross-sectional view through a first embodiment of a circuit device with a contact element for connecting a wave guide to a conductor strip;

Figure 2 is a schematic cutaway cross-sectional view through a second embodiment of a circuit device with a contact element for connecting a wave guide to a conductor strip;

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Figure 3 is a schematic cutaway cross-sectional view through a third embodiment of a circuit device with a contact element for connecting a wave guide to a conductor strip;

Figure 4 is a schematic cutaway cross-sectional view through a fourth embodiment of a circuit device with a contact element for connecting a wave guide to a conductor strip; and

Figure 5 is a schematic cutaway cross-sectional view through a fifth embodiment of a circuit device with a contact element for connecting a wave guide to a conductor strip.

### **Description of the Preferred Embodiments**

A wave guide 1 in the form of a stepping transformer and a conductor strip substrate 2 rest on a metal plate 5. The wave guide is screwed on the metal plate 5. The form of the stepping transformer is not described here in detail. The conductor strip substrate 2 is glued on with the help of an electrically conductive adhesive material or glue 6. The conductor strip substrate 2 is provided on its upper side with a conductor strip 7. This conductor strip is a component of a microwave IC (MIC). The wave guide 1 has a coupling opening 8 in the vicinity of the conductor strip.

According to figure 1 a coil spring 11 operating as an electrically conductive contact element is bonded to the conductor strip 7 at a first contacting area 9 with an electrically conducting glue or adhesive. Silver-filled epoxy resin glue is suitable as the adhesive material. The wave guide 1 is assembled after the coil spring 11 has been bonded with the adhesive, so that the mechanically pre-tensioned coil spring 11, which forms a sliding contact 10 at a second contacting area 9', presses resiliently against a surface 1a of the wave guide 1, which extends substantially perpendicularly to the plane of the conductor strip 7. The contact element forms a low impedance contact between the wave guide 1 and the conductor strip 7. This low impedance connection is required in order to permit an optimum tuning of the coupling of the electromagnetic waves from the

wave guide 1 into the conductor strip 7. Besides the geometry of the junction plays an important roll.

Relative motions, especially thermally dependent relative motions, between the wave guide 1 and the conductor strip 7 are compensated with the help of the sliding contact 10 and the spring force of the coil spring 11. Without this device the contacting areas would be subjected to impermissibly large mechanical stresses.

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Figure 2 illustrates another embodiment for the coil spring 12. This embodiment is similar to the embodiment shown in Fig. 1, but differs from it because the surface 1b of the wave guide 1 on which the coil spring 12 bears is substantially parallel to the conductor strip 7.

This latter situation in regard to Fig. 2 is also true of the third embodiment shown in Fig. 3. In the embodiment shown in Fig. 3 a sliding contact 10 of a coil spring 13 is located in a cavity 1c of the wave guide 1. It is also possible to additionally secure the spring contact in the cavity with a highly flexible electrically conductive glue or adhesive material.

In the embodiment shown in Fig. 4 a coil spring 14 is electrically conductively glued to the wave guide 1, while the sliding contact 10 makes electrical contact on the conductor strip 7 on the other conducting area 9'.

In Figure 5 in a fifth embodiment the coil spring 15 has a curved U-shape.

The coil spring 15 is glued in an electrically conductive manner to a first contacting area 9 on the conductor strip 7. The other contacting area 9' of the coil spring 15 is formed as an electrically conducting adhesive area 16. This adhesive

area 16 can however by highly flexible. The coil spring 15 needed not then be formed so that it is U-shaped.

The disclosure in German Patent Application 199 02 240.2 of January 21, 1999 is incorporated here by reference. This German Patent Application describes the invention described hereinabove and claimed in the claims appended hereinabelow and provides the basis for a claim of priority for the instant invention under 35 U.S.C. 119.

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While the invention has been illustrated and described as embodied in a circuit device with a contact element for electrically connecting a wave guide and a conductor strip in a nearly stress-free manner, it is not intended to be limited to the details shown, since various modifications and changes may be made without departing in any way from the spirit of the present invention.

Without further analysis, the foregoing will so fully reveal the gist of the present invention that others can, by applying current knowledge, readily adapt it for various applications without omitting features that, from the standpoint of prior art, fairly constitute essential characteristics of the generic or specific aspects of this invention.

What is claimed is new and is set forth in the following appended claims.

### We claim:

- 1. A circuit device with a contact element that electrically connects a wave guide
- 2 (1) with a conductor strip (7) by means of two contacting areas (9,9'),
- wherein the contact element consists of a prefabricated coil spring (11 to
- 4 15) having reproducible spring properties, is bonded at one (9) of the contacting
- areas to the wave guide (1) or the conductor strip (7) by means of an electrically
- 6 conductive glue or adhesive, and
- wherein another (9') of the contacting areas is a sliding contact (10),
- whereby the coil spring is pre-tensioned; or is provided by an electrically
- 9 conductive glue or adhesive portion (16), whereby the coil spring (15) is bent into
- a U-shape; or is provided with a highly flexible electrically conductive adhesive
- 11 section (16).
- 2. The circuit device as defined in claim 1, wherein said coil spring (11 to 15) is
- 2 made by means of UV depth lithography and multilayer galvanic methods.
- 3. The circuit device as defined in claim 1, wherein said coil spring (11 to 15) is
- 2 made by laser processing.
- 4. The circuit device as defined in claim 1, wherein said coil spring (11 to 15) is
- 2 made by high precision stamping or punching.

- 5. The circuit device as defined in claim 1, wherein said coil spring (11 to 15) is
- 2 made by means of a batch process.
- 6. The circuit device as defined in claim 1, wherein said wave guide is a stepping
- 2 transformer.
- 7. The circuit device as defined in claim 1, further comprising a conductor strip
- substrate (2) and wherein said conductor strip (7) is mounted on said conductor
- 3 strip substrate (2).
- 8. The circuit device as defined in claim 1, wherein both surfaces (1a,7) of the
- wave guide (1) and the conductor strip (7) contacting the contact element are
- 3 substantially perpendicular to each other.
- 9. The circuit device as defined in claim 1, wherein both surfaces (1a,7) of the
- wave guide (1) and the conductor strip (7) contacting the contact element are
- 3 substantially parallel to each other.



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### ABSTRACT OF THE DISCLOSURE

The circuit device has a contact element which electrically connects a wave guide (1) with a conductor strip (2) by means of two contacting areas. To avoid mechanical stresses due to thermal expansion the contact element is formed as a precisely prefabricated coil spring having reproducible properties, which is connected at one of the contacting areas to the wave guide (1) or the conductor strip (2) by means of an electrically conducting adhesive or glue, while the second contacting area is provided as a sliding contact, whereby the coil spring is pre-stressed.





PTO/SB/103 (8-96)

Approved for use through 9/30/98. OMB 0651-0032
Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

# Declaration and Power of Attorney for Patent Application Erklärung für Patentanmeldungen mit Vollmacht

## GermanLanguageDeclaration

Als nachstehend benannter Erfinder erkläre ich hiermit an Eides Statt: Bernhard LUCAS Frank SCHATZ Juergen SEIZ Heinz EISENSCHMID Andreas KUGLER Achim DIETERICH

dass mein Wohnsitz, meine Postanschrift und meine Staatsangehörigkeit den im nachstehenden nach meinem Namen aufgeführten Angaben entsprechen, dass ich nach bestem Wissen der ursprüngliche, erste und alleinige Erfinder (falls nachstehend nur ein Name angegeben ist) oder ein ursprünglicher, erster und Miterfinder (falls nachstehend mehrere Namen aufgeführt sind) des Gegenstandes bin, für den dieser Antrag gestellt wird und für den ein Patent für die Erfindung mit folgendem Titel beantragt wird:

### **SCHALTUNGSANORDUNG**

deren Beschreibung hier beigefügt ist, es sei denn (in diesem Falle Zutreffendes bitte ankreuzen), diese Erfindung

	wurde angemeldet am		
	unter der US-Anmeldenummer oder unter der Internationalen Anmeldenummer im Rahmen des		
	Vertrags über die Zusammenarbeit auf dem Gebiet des		
	Patentwesens (PCT)		
	und am		
	abgeändert (falls		
	zutreffend).		
	·		

Ich bestätige hiermit, dass ich den Inhalt der oben angegebenen Patentanmeldung, einschliesslich der Ansprüche, die eventuell durch einen oben erwähnten Zusatzantrag abgeändert wurde, durchgesehen und verstanden habe.

Ich erkenne meine Pflicht zur Offenbarung jeglicher Informationen an, die zur Prüfung der Patentfähigkeit in Einklang mit Titel 37, § 1.56 von Belang sind. As a below named inventor, I hereby declare that:
Bernhard LUCAS
Frank SCHATZ
Juergen SEIZ
Heinz EISENSCHMID
Andreas KUGLER
Achim DIETERICH

My residence, post office address and citizenship are as stated next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

### CIRCUIT DEVICE WITH A CONTACT ELEMENT FOR ELECTRICALLY CONNECTING A WAVE GUIDE AND A CONDUCTIOR STRIP IN A NEARLY STRESS-FREE MANNER

the specification of which is attached hereto unless the following box is checked:

	was filed on	
	as United States Application Number or PC	T
	International Application Number	
	and was amended on	
(if	applicable)	

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Code of Federal Regulations, Regulations, § 1.56.







### GermanLanguageDeclaration

Ich beanspruche hiermit ausländische Prioritätsvorteile gemäss Title 35, US-Code, § 119 (a)-(d), bzw. § 365(b) aller unten aufgeführten Auslandsanmeldungen für Patente oder Erfinderurkunden, oder § 365(a)aller PCT internationalen Anmeldungen, welche wenigstens ein Land ausser den Vereinigten Staaten von Amerika benennen, und habe nachstehend durch ankreuzen sämtliche Auslandsanmeldungen für Patente bzw. Erfinderurkunden oder PCT internationale Anmeldungen angegeben, deren Anmeldetag dem der Anmeldung, für welche Priorität beansprucht wird, vorangeht.

I hereby claim foreign priority under Title 35, United States Code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed.

Prior Foreign Applications (Frühere ausländische Anmeldungen)

1 99 02 240.2	GERMANY
(Number)	(Country)
(Nummer)	(Land)
(Number) (Nummer)	(Country) (Land)

(Tag/Monat/Jahr der Anmeldung)

JANUARY 21, 1999□ (Day/Month/Year Filed) (Tag/Monat/Jahr der Anmeldung)

(Day/Month/Year Filed)

Ich beanspruche hiermit Prioritätsvorteile unter Title 35, US-Code, § 119(e) aller US-Hilfsanmeldungen wie unten aufgezählt.

(Application No.) (Filing Date)
(Akzenzeichen) (Anmeldetag)

Ich beanspruche hiermit die mir unter Title 35, US-Code, § 120 zustehenden Vorteile aller unten aufgeführten US-Patentanmeldungen bzw. § 365(c) aller PCT internationalen Anmeldungen, welche die Vereinigten Staaten von Amerika benennen, und erkenne, insofern der Gegenstand eines jeden früheren Anspruchs dieser Patentanmeldung nicht in einer US-Patentanmeldung, bzw. PCT internationalen Anmeldung in in einer gemäss dem ersten Absatz von Title 35, US-Code, § 112 vorgeschriebenen Art und Weise offenbart wurde, meine Pflicht zur Offenbarung jeglicher Informationen an, die zur Prüfung der Patentfähigkeit in Einklang mit Title 37, Code of Federal Regulations, § 1.56 von Belang sind und die im Zeitraum zwischen dem Anmeldetag der früheren Patentanmeldung und dem nationalen oder im Rahmen des Vertrags über die Zusammenarbeit auf dem Gebiet des Patentwesen (PCT) gültigen internationalen Anmeldetags bekannt geworden sind.

(Application No. )
(Akzenzeichen)

(Application No. )
(Application No. )
(Akzenzeichen)

(Anmeldentag)

Ich erkläre hiermit, dass alle in der vorliegenden Erklärung von mir gemachten Angaben nach bestem Wissen und Gewissen der Wahrheit entsprechen, und ferner dass ich diese eidesstattliche Erklärung in Kenntnis dessen ablege, dass wissentlich und vorsätzlich falsche Angaben oder dergleichen gemäss § 1001, Title 18 des US-Code strafbar sind und mit Geldstrafe und/oder Gefängnis bestraft werden können und dass derartige wissentlich und vorsätzlich falsche Angaben die Rechtswirksamkeit der vorliegenden Patentanmeldung oder eines aufgrund deren erteilten Patentes gefährden können..

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s)listed below.

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

(Status) (patented, pending, abandoned) (Status) (pateniert, schwebend, aufgegeben)

(Status) (patented, pending, abandoned) (Status) (pateniert, schwebend, aufgegeben)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief arebelieved to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title

18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.



VERTRETUNGSVOLMACHT: Als benannter Erfinder beauftrage ich hiermit den (die) nachstehend aufgeführten Patentanwalt (älte) und/oder Vertreter mit der Verfolgung der vorliegenden Patentanmeldung sowie mit der Abwicklung aller damit verbundenen Angelegenheiten vor dem US-Patent- und Markenamt: (Name(n) und Registrationsnummer(n) auflisten)

Michael J. Striker, Registration No. 27233 Ilya Zborovsky, Registration No. 28563 William G. Valance, Registration No.: 28275

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Michael J. Striker (631) 549 4700 POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: (list name and registration number)

Michael J. Striker, Registration No. 27233 Ilya Zborovsky, Registration No. 28563 William G. Valance, Registration No.: 28275

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Michael J. Striker (631) 549 4700

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Unterschrift des Erfinders  Datum  28.1.00	Prentor's signature Date 28, 1,00		
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Unterschrift des Erfinders Datum  Frank Ydah 3. 2. 2000	Second inventor's signature Date  Frank Ydah 2000/2/4		
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Juergen SEIZ	Juergen SEIZ		

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Unterschrift des Erfinders Datum  4.2.2000	Fourth inventor's signature Date .  Hans Eusland 20w1214
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Unterschrift des Erfinders Datum	Fifth inventor's signature Date
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1 4.

Unterschrift des Erfinders Datum 31. 1.00	Sixth inventor's signature Date 31. 01.00
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Staatangehörtigkeit	Citizenship GERMAN
GERMAN	•
Postanschrift TECKSTR. 13 73553 ALFDORF,GERMANY	Post Office Address TECKSTR.13 73553 ALFDORF,GERMANY
Vor- und Zumane des siebtens Erfinders (falls zutreffend)	Full name of seventh joint inventor, if any
Unterschrift des Erfinders Datum	Seventh inventor's signature Date
Staatangehörtigkeit	Citizenship
Postanschrift	Post Office Address
Vor- und Zumane des achtens Erfinders (falls zutreffend)	Full name of eighth joint inventor, if any
Unterschrift des Erfinders Datum	Eighth inventor's signature Date
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